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| CO-007                    | Pin Grid Array Pkg., .100" Centers   | A                       | October 1987   |
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| CO-017                    | Metric TAB Magazine Family   | A                       | August 1991    |
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| MO-004 AG                 | <b>Replaced by MS-033 Variation AC</b>                | A                       | November 1999     |
| MO-004 AH                 | <b>Replaced by MS-033 Variation AC</b>                | A                       | November 1999     |
| MO-004 AJ                 | <b>Replaced by MS-033 Variation AB</b>                |                         |                   |
| MO-004 AK                 | <b>Replaced by MS-033 Variation AA</b>                | A                       | November 1999     |
| MO-004 AL                 | <b>Replaced by MS-033 Variation AC</b>                | A                       | November 1999     |
| MO-004 AM                 | Flatpack Family .300" Width, .050" Pitch              | C                       | November 1999     |
|                           | <b>RESCINDED</b>                                      |                         |                   |
| MO-005                    | Grid Array Family, .125" Pitch                        | B                       | Archived – JEP 95 |
| MO-006 AA-AD              | Header Family 5.842 mm Pin Circle                     | C                       | October 1976      |
| MO-006 AE-AH              | Header Family 5.842 mm Pin Circle                     | D                       | October 1976      |
| MO-007                    | Header Family, .141" Pin Circle                       | B                       | Archived – JEP 95 |
| MO-008                    | Header Family, .100" Pin Circle                       | B                       | Archived – JEP 95 |
| MO-009 AA-AB              | Header Family, .200 Pin Circle                        | C                       | Archived – JEP 95 |
| MO-010                    | Header Family, .065" Pitch                            | B                       | Archived – JEP 95 |
| MO-011                    | Grid Array Family, 2.54 mm Pitch                      | B                       | Archived – JEP 95 |
| MO-012 AA-AB              | Quad Header Family, 2.54 mm Pitch                     | C                       | Archived – JEP 95 |
| MO-013                    | Header Family, 11.89 mm Pin Circle                    | B                       | Archived – JEP 95 |
| MO-014                    | Flange-Mounted Family Axial Lead                      | C                       | October 1976      |
| MO-015 AA-AD              | Dual In Line (DIP) Family 15.24 mm Row Spacing        | D                       | June 1976         |
| MO-015 AE-AH              | Dual In Line (DIP) Family 15.24 mm Row Spacing        | E                       | June 1977         |
| MO-015 AJ-AM              | Dual In Line (DIP) Family 15.24 mm Row Spacing        | E                       | February 1981     |
| MO-015                    | R-PDIP-T Dual Inline Plastic Family .600" Row Spacing | G                       | April 1993        |
| MO-016                    | Dual In Line Plastic Family .900" Row Spacing         | D                       | May 1990          |

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| MO-017                    | Axial Quad Family 2.54 mm Pitch  | B                       | October 1976   |
| MO-018                    | Flatpack Family 10.16 mm Width, .89 Pitch                                    | C                       | June 1976      |
| MO-019 AA                 | <b>Replaced by MS-033 Variation AE</b>                                       | A                       | November 1999  |
| MO-019 AB                 | <b>Replaced by MS-033 Variation AF</b>                                       | A                       | November 1999  |
| MO-019 AC                 | <b>Replaced by MS-033 Variation AE</b>                                       | A                       | November 1999  |
| MO-019 AD                 | <b>Replaced by MS-033 Variation AF</b>                                       | A                       | November 1999  |
| MO-019 AE                 | Flatpack Family 10.16 mm Width, 1.27 Pitch<br><b>RESCINDED</b>               | D                       | November 1999  |
| MO-019 AF                 | <b>Replaced by MS-033 Variation AF</b>                                       | A                       | November 1999  |
| MO-020                    | Flatpack Family 12.70 mm Width, 1.27 Pitch                                   | C                       | June 1976      |
| MO-021                    | Flatpack Family 15.24 mm Width, 1.27 Pitch                                   | C                       | June 1976      |
| MO-022 AA-AD              | Flatpack Family 17.780 mm Width, 1.27 Pitch                                  | D                       | September 1977 |
| MO-022 AE                 | Flatpack Family 17.780 mm Width, 1.27 Pitch                                  | A                       | September 1977 |
| MO-023                    | Flatpack Family 22.86 mm Width, 1.27 Pitch                                   | C                       | June 1976      |
| MO-024                    | Dual In Line (DIP) Family 12.70 mm Row Spacing                               | C                       | June 1976      |
| MO-025                    | Flange Mounted Family Axial Lead 12.70 Pin Circle                            | B                       | October 1976   |
| MO-026                    | Standard Dual-in-Line Family .400" Row Spacing<br>(Plastic) .070" Lead Pitch | D                       | July 1991      |
| MO-027                    | Leadless Flatpack Family 1.27 mm Terminal Space                              | A                       | February 1977  |
| MO-028                    | Dual In Line (DIP) Family 5.08 mm Row Spacing                                | B                       | October 1976   |
| MO-029                    | Quad In Line (QUIP) Family 5.08/10.16 mm Row<br>Spacing                      | B                       | October 1976   |
| MO-030                    | Quad In Line (QUIP) Family 19.05/23.50 mm Row<br>Spacing                     | B                       | October 1976   |
| MO-031                    | Quad In Line (QUIP) Family 5.08/10.16 mm Row<br>Spacing                      | D                       | October 1979   |
| MO-032 AA-AF              | Flatpack Family 16.64 mm Width, 1.27 Pitch                                   | C                       | February 1981  |
| MO-033                    | Quad In Line (QUIP) Family 17.78/22.86 mm Row<br>Spacing                     | B                       | February 1981  |
| MO-034                    | Quad In Line (QUIP Family) .750/.925" Row<br>Spacing                         | C                       | June 1990      |
| MO-035                    | Single In Line (SIP) Family  | A                       | September 1980 |
| MO-036                    | Ceramic Dual-In-Line (DIP) Family .300" Row<br>Spacing                       | B                       | November 1999  |
| MO-037                    | <b>Replaced by MS-031</b>  |                         |                |
| MO-038                    | Replaced by MS-032   |                         |                |
| MO-039                    | Ceramic Side Ledged Dual In Line (DIP) Family<br>22.86 mm Row Spacing        | A                       | April 1981     |
| MO-040                    | Power Module   | C                       | May 1983       |
| MO-041 AA-AF              | .050" Pitch Leadless Rectangular Chip Carrier<br>Family (R-CQCC-N)           | C                       | February 1995  |



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| MO-042            | .050" Center Leadless Rectangular Chip Carrier<br>Type F                     | A               | February 1983  |
| MO-043            | Dual In Line Package 19.05 mm Row Spacing                                    | A               | September 1984 |
| MO-044            | Leaded Ceramic Chip Carrier .050" Center                                     | A               | September 1984 |
| MO-045            | Single In Line Power Module  | A               | September 1984 |
| MO-046            | Small Outline (SO) Package Peripheral Terminals<br>5.30 mm (.200") Wide Body | B               | November 1984  |
| MO-047            | Plastic Chip Carrier (PCC) Family .050"<br>Leadspacing, Square               | B               | November 1988  |
| MO-048            | Plastic Flange-Mounted Header Family Multilead<br>Registration               | A               | February 1987  |
| MO-049            | <b>Not Published</b>   |                 |                |
| MO-050            | <b>Not Published</b>   |                 |                |
| MO-051            | <b>Not Published</b>   |                 |                |
| MO-052            | <b>Replaced by MS-016</b>  |                 |                |
| MO-053            | <b>Replaced by MO-069</b>  |                 | September 1988 |
| MO-054            | Zig-Zag (ZIP) In Line Family 2.54mm Row Spacing                              | A               | June 1986      |
| MO-055            | Ceramic Single In Line (SIP) Family  | A               | August 1986    |
| MO-056            | Ceramic .025" Center Chip Carrier  | A               | August 1986    |
| MO-057            | Ceramic .020" Center Chip Carrier  | A               | August 1986    |
| MO-058 AA         | <b>Replaced by MS-030 AF</b>   |                 |                |
| MO-058 AB         | <b>Replaced by MS-030 AG</b>   |                 |                |
| MO-059            | Small Outline (SO) Package Family 8.4 mm Body<br>Width (Plastic)             | B               | January 1987   |
| MO-060            | .040" 132 Pin Quad Flatpack  | B               | November 1989  |
| MO-061            | <b>Replaced by MS-027</b>  |                 | June 1995      |
| MO-062            | Ceramic Chip Carrier 0.25" Center  | A               | April 1987     |
| MO-063            | Plastic Small Outline J-Lead (SOJ) .350" Body                                | A               | April 1987     |
| MO-064            | 30 Circuit Pluggable Single Inline Package (SIP)<br>Tabs on .100" Centers    | C               | September 1992 |
| MO-065            | Plastic Small Outline J-Lead (SOJ) .300 Body<br>Family                       | A               | May 1987       |
| MO-066            | S-CPGA-P Pin Grid Array Family, .100" Pitch<br>(Small Outline)               | C               | April 1994     |
| MO-067            | Pin Grid Array Family, .100" Pitch (Large Outline),<br>S-CPGA-P              | B               | June 1993      |
| MO-068            | Edge Clip SIP Module Family .100 Row Centers                                 | B               | August 1991    |
| MO-069            | Plastic Quad Flat Pack .025" Lead Spacing<br>(Gullwing)                      | B               | October 1990   |
| MO-070            | .375" Width Flatpack <b>NOT PUBLISHED</b>                                    | A               | August 1987    |
| MO-071            | Plastic Thin Lead Package  | B               | July 1989      |

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| MO-072                    | Zig-Zag Inline Family (ZIP) 0.500" Max Seated Height                                    | B                       | September 1990 |
| MO-073                    | Ceramic Top Brazed Dual In Line (DIP) Family<br>.900 (22.86) Row Spacing                | A                       | November 1987  |
| MO-074                    | Ceramic Bottom Brazed Dual In Line (DIP) Family<br>.900 (22.86) Row Spacing             | A                       | November 1987  |
| MO-075                    | .50 Center Non-Hermetic Leadless Chip Carrier<br>Quad Series                            | A                       | December 1987  |
| MO-076                    | .050 Center Non-Hermetic Leadless Chip Carrier SO<br>Series                             | A                       | December 1987  |
| MO-077                    | Plastic Small Outline J-Lead Package Family (SOJ),<br>.300" Wide Body, .050" Lead Pitch | D                       | November 1994  |
| MO-078                    | Hermetic Flange-Mounted Header Family<br>(Peripheral Terminals) Five Lead 2.54 Spacing  | A                       | February 1988  |
| MO-079                    | Flanged Family Peripheral lead .125 Pitch   | A                       | March 1988     |
| MO-080 AA-AB              | ZIP Module Family 0.050" Pin Centers 0.100" Row<br>Centers                              | A                       | September 1988 |
| MO-081                    | Ceramic Quadpack Family .050" Pitch   | A                       | March 1988     |
| MO-082                    | Ceramic Quad Flat Pack .025" Lead Spacing<br>(Gullwing)                                 | A                       | May 1988       |
| MO-083                    | .100" Center Plastic Pin Grid Array Family  | A                       | December 1988  |
| MO-084                    | Ceramic Quad Flat Pack 0.50" Lead Spacing<br>(Gullwing)                                 | A                       | July 1988      |
| MO-085                    | .040" Center Rectangular Leadless Package<br>(Staggered Terminals)                      | A                       | July 1988      |
| MO-086                    | Low Profile Plastic Quad Flat Pack Family .025<br>Lead Spacing (Gullwing)               | B                       | June 1990      |
| MO-087                    | "J" Leaded Ceramic Cerquad Package Family -<br>.050" Pitch                              | B                       | August 1991    |
| MO-088 AA-AF              | Small Outline J-Lead (SOJ) .300 Body Family<br>(MS-113 body)                            | A                       | June 1988      |
| MO-089                    | Plastic Quad Flat Pack .050" Lead Spacing<br>(Gullwing)                                 | A                       | November 1988  |
| MO-090 AA-AF              | Ceramic Quadpack Family .025" Lead Spacing  | B                       | September 1989 |
| MO-091                    | Plastic Small Outline J-Lead (SOJ) .350 Body<br>Family                                  | A                       | February 1989  |
| MO-092                    | 6.35 Mm Width Cerpak Registration   | A                       | April 1989     |
| MO-093                    | Flange-Mounted Header, 5-Lead   | A                       | February 1990  |
| MO-094                    | Molded Carrier Ring Family  | C                       | March 1993     |
| MO-095                    | Dual Incline (Wide Body) Plastic Family .300" Row<br>Spacing                            | A                       | September 1989 |

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| MO-096                    | Flange-Mounted Header, 7-Lead   | A                       | February 1990  |
| MO-097                    | Flange-Mounted Family Axial Lead .500" Pin Circle   | A                       | July 1989      |
| MO-098                    | Braze Lead Flatpack Registration  | A                       | December 1989  |
| MO-099                    | Small Outline (SO) Family Peripheral  | A                       | October 1989   |
| MO-100                    | Multilayer Ceramic Quad Flatpack .20 Spacing<br>Gullwing (256 leads)                      | A                       | November 1989  |
| MO-101                    | 48 Pin Flatpack, Top Brazed   | A                       | November 1989  |
| MO-102                    | Tape Quad Flatpack <b>RESCINDED</b>   | A                       | November 1992  |
| MO-103                    | <b>Replaced by MS-032</b>   | B                       | August 1999    |
| MO-104                    | Ceramic Quad Flatpack, 0.25" Pitch, Gullwing<br>Leadform                                  | A                       | August 1991    |
| MO-105                    | Thin Small Outline J-Lead (TSOJ) .300" Body,<br>0.050" Lead Pitch                         | A                       | August 1990    |
| MO-106                    | Flatpack Family .535" Length, .030 Pitch  | A                       | April 1990     |
| MO-107                    | Ceramic Multilayer Leaded Chip Carrier .050"<br>Pitch, J-Bend                             | A                       | May 1990       |
| MO-108                    | Metric Plastic Quad Flat Pack Family, 1.0, 0.8, 0.65<br>Pitch PQFP-G/MQFP                 | C                       | August 1996    |
| MO-109                    | Molded Carrier Ring Family  | B                       | March 1993     |
| MO-110                    | Round Lead, "J" form .050" Center Ceramic Chip<br>Carrier                                 | A                       | July 1990      |
| MO-111                    | Round Lead, Gullwing .050" Center Ceramic Chip<br>Carrier                                 | A                       | July 1990      |
| MO-112                    | Metric Plastic Quad Flatpack Family 3.9 mm<br>Footprint                                   | B                       | September 1995 |
| MO-113                    | Ceramic Quadpack Family 0.25" Lead Spacing With<br>Ceramic Nonconductive Tie Bar          | D                       | August 1997    |
| MO-114                    | Glass Sealed CQFP Family (GQFP-G)   | C                       | January 1996   |
| MO-115                    | 32 Ld. Flatpack .480" Wide  | A                       | November 1990  |
| MO-116                    | Pluggable Single In-Line Memory Module (SIMM)<br>With Tabs on .050 Centers                | B                       | June 1998      |
| MO-117                    | Small Outline Gullead 12 mm Body 0.80 mm Lead<br>Spacing                                  | A                       | June 1990      |
| MO-118                    | Shrink Small Outline Package Family, 0.25" Lead<br>Pitch .300" Wide Body Width (R-PDSO-G) | B                       | June 1993      |
| MO-119                    | Plastic Small Outline (SO) Package Family With<br>.300" Body Width                        | B                       | May 1992       |
| MO-120                    | Plastic Small Outline (SO) Package Family With<br>.350" Body Width                        | B                       | May 1992       |
| MO-121                    | Plastic Small Outline (SO) Package Family With<br>.330" Body Width                        | B                       | May 1992       |

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| MO-122                    | R-PDIP-T Thin Dual In Line Family .300" Row Spacing (Plastic)                                 | A                       | August 1992    |
| MO-123                    | Small Outline J-Lead, 12 mm Body 0.80 mm Lead Spacing   | A                       | June 1991      |
| MO-124                    | Small Outline J-Lead Package Family (SOJ) 12.70 mm Body, 1.27 mm Lead Spacing                 | B                       | January 1994   |
| MO-125                    | Ceramic Quad Flatpack .025" Pitch Gullwing Leadform   | A                       | June 1991      |
| MO-126                    | R-CDCC-N Leadless Small Outline Ceramic Chip Carrier .400" Body, .050" Pitch                  | B                       | June 1993      |
| MO-127                    | Power Dual In-line  | A                       | February 1992  |
| MO-128 AA-BQ              | .100" Center Staggered Pin Grid Array Family (Large Outline)                                  | C                       | January 1997   |
| MO-129                    | Top Brazed Ceramic Leaded Chip Carrier (.020" Lead Pitch) with Plastic Non-Conductive Tie Bar | A                       | September 1992 |
| MO-130                    | Top Brazed Ceramic Leaded Chip Carrier (.015" Lead Pitch) with Plastic Non-Conductive Tie Bar | A                       | September 1992 |
| MO-131                    | Top Brazed Ceramic Leaded Chip Carrier (.025" Lead Pitch) with Plastic Non-Conductive Tie Bar | A                       | September 1992 |
| MO-132                    | <b>Replaced by MS-025A</b>  |                         |                |
| MO-133                    | <b>Replaced by MS-024</b>   |                         | January 1995   |
| MO-134                    | Ceramic Quad Flatpack Family (CQFP) 0.50 mm Lead Pitch with Ceramic Nonconductive Tie Bar     | A                       | May 1992       |
| MO-135                    | Thin Small Outline Package 12.70 mm Body Family (R-PDSO-G/TSOP II)                            | C                       | November 1993  |
| MO-136                    | <b>Replaced by MS-026</b>   |                         |                |
| MO-137                    | Plastic Shrink Small Outline Package (SSOP) Family 0.025" pitch 0.150" Body Width             | E                       | March 2010     |
| MO-138                    | 16 Lead Flange Mounted Ceramic Power Package (Type 1), R-CDFM-T16                             | A                       | June 1993      |
| MO-139                    | 16 Lead Flange Mounted Ceramic Power Package (Type 2), R-CDFM-T16                             | A                       | June 1993      |
| MO-140                    | 18 Lead Flange Mounted Ceramic Power Package, R-CDFM-T16                                      | A                       | June 1993      |
| MO-141                    | Vertical Surface Mount Package 0.50 mm Lead Pitch, R-PSIP-X24                                 | A                       | March 1993     |
| MO-142                    | Thin Small Outline Package Type I, R-PDSO-G/TSOPII  | D                       | July 2000      |
| MO-143                    | <b>Replaced by MS-029</b>   |                         | June 1997      |
| MO-144                    | Leadless Small Outline Ceramic Chip Carrier .350" Body, .050" Pitch, R-CDCC-N                 | A                       | June 1993      |

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| MO-145            | S-CPGA-B/SMTPGA .050 Center Ceramic Surface Mount Pin Grid Array Family Registration                        | A               | June 1993      |
| MO-146            | Ceramic Flatpack Family .380" Width, .025 Pitch (R-GDFP-F)  | A               | July 1993      |
| MO-147            | Small Outline J-Lead Ceramic Chip Carrier .415" Body, .050" Lead Spacing (R-CDSO-J)                         | A               | July 1993      |
| MO-148            | Multichip Module Ceramic Quad Flatpack (S-CQFP)   | A               | June 1993      |
| MO-149            | Tape Ball Grid Array Family   | F               | October 2003   |
| MO-150            | Plastic Shrink Small Outline Package (SSOP) - 5.3mm Body Width, 0.65mm Pitch, 1.25mm Lead Length (R-PDSO-G) | B               | January 1994   |
| MO-151            | <b>Replaced by MS-034</b>   |                 |                |
| MO-152            | Plastic Shrink Small Outline Package (SSOP), R-PSDO-G/SSOP  | C               | January 1996   |
| MO-153            | Plastic Thin Shrink Small Outline Package (SSOP) R-PDSO-G/TSSOP/HTSSOP                                      | G               | January 2018   |
| MO-154            | Shrink Small Outline Package Family, 0.4 mm and .5 mm Lead Pitch, 3.9 mm Wide Body                          | C               | April 1997     |
| MO-155            | 5-Lead Small Outline Plastic (SOP) Package  | A               | November 1993  |
| MO-156            | Square Ceramic Ball Grid Array Family 1.00, 1.27, and 1.50 mm Pitch   | C               | April 2005     |
| MO-157            | Rectangular Ceramic Ball Grid Array Family 1.00, 1.27, and 1.50 mm Pitch                                    | C               | April 2005     |
| MO-158            | CBGA-X Ceramic Column Grid Array Family - Square  | D               | April 2002     |
| MO-159            | Ceramic Column Grid Array Family - Rectangular  | B               | June 1999      |
| MO-160 AA-CC      | 72-Contact Dual Inline Memory Module (DIMM) Family, 1.27 Lead Centers                                       | B               | September 1995 |
| MO-161            | 100 and 168 Pin Dual Inline Memory Module (DIMM) Family with Multiple Keyways, 1.27 mm Contact Centers      | Ff              | January 2003   |
| MO-162            | Plastic Flat Pack/Heat Slug Package 8 mm Pitch 48 Leads (S-PTFP-G48)  | A               | November 1993  |
| MO-163            | <b>Replaced by MS-028</b>   |                 | December 1997  |
| MO-164            | Plastic Small Outline Package, 9.90 mm Wide Body Family (R-PDSO-G)  | A               | January 1994   |
| MO-165            | Plastic Small Outline J-Lead, 10.15mm Body Family, .8mm Pitch   | C               | September 1996 |
| MO-166 AA-AF      | Plastic Small Outline Heat Slug Package, 20, 24, 30, 36 Leads   | D               | November 1999  |

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| MO-167            | Pluggable Dual Inline Module, 1.27 mm Lead<br>Centers 128-Pins                                 | C               | October 1997   |
| MO-168 AA-AB      | Plastic Isolated Flange-Mounted Header Family  | A               | January 1994   |
| MO-169            | Plastic Surface Mounted Header Family  | B               | November 2000  |
| MO-170            | 68-Pin Card  | A               | February 1995  |
| MO-171            | 88-Pin Card  | A               | February 1995  |
| MO-172            | Dual Inline Memory Module (DIMM) Family 112 &<br>300 Pin 1.27 mm Pitch                         | D               | April 1999     |
| MO-173            | TFH-PQFP-G/TQHS Thin Quad Heat Spreader<br>Family Registration                                 | A               | October 1995   |
| MO-174            | Plastic Small Outline Package, 70-pin .8 mm Pitch<br>(R-PDSO-G/SOP)                            | A               | January 1996   |
| MO-175            | Plastic Small Outline Package, 12.6 mm Body, 1.27<br>mm Lead Spacing                           | A               | September 1995 |
| MO-176            | Ceramic Zig-Zag Inline Family (2.54 Row Spacing)   | A               | March 1995     |
| MO-177            | 200 Pin Small Outline Dual Inline Memory Module<br>(DIMM) Family, 0.65 mm Lead Centers         | A               | July 2001      |
|                   | <b>RESCINDED</b>   |                 |                |
| MO-178            | Plastic Small Outline Package (SOT/SP), 5 Leads  | C               | February 2000  |
| MO-179            | Dual Inline Memory Module (DIMM) Family 1.00<br>Lead Centers (278-pin)                         | A               | October 1995   |
| MO-180            | Plastic Small Outline Package (SOP) 13.3 mm Body<br>Width                                      | B               | February 2001  |
| MO-181            | Metric Small Outline 16 mm Wide Body J-Lead<br>Package (MSOJ)                                  | A               | January 1996   |
| MO-182            | Metric Thin Small Outline 16.00 mm Wide Body<br>Package (MTSOP II)                             | C               | September 1996 |
| MO-183            | Thin Small Outline Package Type I 0.55 mm Lead<br>Pitch (TSOP I)                               | A               | January 1996   |
| MO-184            | Plastic Small Outline Heat Slug Package  | B               | November 1999  |
| MO-185            | 72 Pin Staggered Dual Inline Module (SDIM)<br>Family, 1.27 Lead Centers                        | A               | August 1996    |
| MO-186            | Solid State Floppy Disk Card (SSFDC)   | C               | March 1999     |
| MO-187            | Plastic Thin Shrink Small Outline Package 0.65 &<br>0.50 Pitch                                 | F               | September 2010 |
| MO-188            | Power PQFP Heat Slug Package (H-PQFP - G)  | B               | February 2000  |
| MO-189            | Plastic Quad Flat Heat Slug Package (2.0mm Thick<br>2.00 mm Footprint Quad & Dual-Sided Leads) | A               | March 1996     |
| MO-190            | Small Outline Dual Inline Memory Module (DIMM)<br>Family, 0.8 Lead Centers                     | D               | January 2001   |
| MO-191            | Dual Inline Memory Module (DIMM) Family 1.27   | A               | December 1996  |

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|                           | Lead Centers, 160 Leads  |                         |                |
| MO-192                    | Low Profile Ball Grid Array Family   | F                       | August 2003    |
| MO-193                    | Plastic Thin Shrink Small Outline Package (Shrink SOT)   | E                       | July 2013      |
| MO-194                    | Plastic Thin Shrink Small Outline Package 0.40mm Lead Pitch  | B                       | November 1997  |
| MO-195                    | Thin Fine Pitch Ball Grid Array, 0.50mm Pitch  | D                       | May 2006       |
| MO-196                    | Plastic Ultra-Thin Small Outline No-Lead Package   | C                       | June 1998      |
| MO-197                    | Plastic Ultra-Thin Small Outline No-Lead Package   | B                       | November 1997  |
| MO-198                    | PQFP-B 3-Tier Family   | A                       | April 1997     |
| MO-199                    | Low Profile Small Outline J-Lead Package (LSOJ)  | B                       | June 1999      |
| MO-200                    | Small Outline J-Lead Package Assembly 2 High/4 High Stack  | B                       | June 1999      |
| MO-201                    | 2 High/4 High Stacked TSOP II <b>INACTIVATION NOTICE</b>   | A                       | June 2003      |
| MO-202                    | Vertical Zig Zag Surface Mount Package 0.40mm Lead Pitch   | A                       | March 1998     |
| MO-203                    | Plastic Thin Shrink Outline Package (Shrink SOT)   | C                       | August 2010    |
| MO-204                    | Plastic Quad Flat Package Outline With Exposed Heat Sink   | B                       | May 2001       |
| MO-205                    | Low Profile, Fine Pitch, Ball Grid Array Family, 0.80mm Pitch, (Sq. & Rect.)                         | F                       | April 2003     |
| MO-206                    | Dual Inline Memory Module (DIMM) Family 184 Pin DDR 1.27mm Contact Centers                           | E                       | January 2006   |
| MO-207                    | Square & Rectangular Die-Size Ball Grid Array Family   | N                       | June 2013      |
| MO-208                    | Plastic Thin Fine Pitch Quad Flat No Lead Package  | C                       | November 2001  |
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